MY SDL Journey form

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Course of Study: DASE / DCPE / DEB / DEEE

Name of Company: Micron Semiconductor Asia Pte. Ltd.

[A] Weeks 1 to 5: My learning (Goals, challenges and strategies/ resources used)

- Learning the assembly line process
- Understanding deeply on flip-chip process and defects
- Learn basic python coding using YouTube tutorials.
- Aimed to create a Image Classification Machine Learning Model, however due to image complexity and low intensity models, models achieved low accuracy and low precision. I had to use new methods from Github to solve the issue

[B] LO 1st visit: Record of feedback received on [A]

- · Keep expanding knowledge base.
- Continue working on project.

Student Signature:

Date: 9 April 2024

[C] Weeks 6 to 11: Record of follow-up actions on [B] with evidence/result (to be shared during LO 2nd visit)

 Pivoted from current project approach to create an image analysis program instead.

[D] Weeks 6 to 11: My learning (Goals, challenges and strategies/ resources used)

- Aimed to create a heatmap and web deployed application for defect analysis, I
 had issues with the approach to the problem hence had to constantly pivot and
 adjust calculations from there. Using Copilot, I was able to troubleshoot and
 debug issues quickly.
- Aimed to develop a file conversion program to convert unreadable text files to csv format. Had issues regarding permission errors, query times for filtering, file sizes and complexity of data. Through trial and error, I was able to create a highly efficient and effective file conversion program.

[E] LO 2nd visit: Record of feedback received on [C] and [D]

- Good Job, continue working hard.
- Ensure proper documentation of code and maintenance.

Student Signature: Date: 6 June 202

[F] Weeks 13 to 21: Record of follow-up actions on [E] with evidence/result (to be shared with LO during $3^{\rm rd}$ visit)

 Created slides, FAQs, and videos for troubleshooting and simple maintenance of software.

Student Signature: Date: 31 July 2024